

International Rectifier

IRFI9Z34N

- Advanced Process Technology
- Isolated Package
- High Voltage Isolation = 2.5KVRMS ⑤
- Sink to Lead Creepage Dist. = 4.8mm
- P-Channel
- Fully Avalanche Rated

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

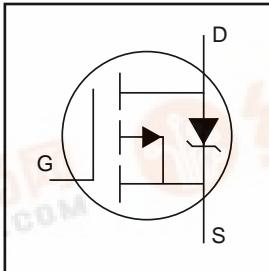
The TO-220 Fullpak eliminates the need for additional insulating hardware in commercial-industrial applications. The moulding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The Fullpak is mounted to a heatsink using a single clip or by a single screw fixing.

Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}$	-14	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}$	-10	
I_{DM}	Pulsed Drain Current ①⑥	- 68	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	37	W
	Linear Derating Factor	0.24	W/ $^\circ\text{C}$
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②⑥	180	mJ
I_{AR}	Avalanche Current ①⑥	-10	A
E_{AR}	Repetitive Avalanche Energy ①	3.7	mJ
dv/dt	Peak Diode Recovery dv/dt ③⑥	-5.0	V/ns
T_J	Operating Junction and	-55 to + 175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Mounting torque, 6-32 or M3 screw	300 (1.6mm from case)	
		10 lbf-in (1.1N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case	—	4.1	$^\circ\text{C/W}$
$R_{θJA}$	Junction to Ambient	—	65	$^\circ\text{C/W}$

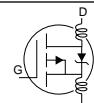


$V_{DSS} = -55\text{V}$
$R_{DS(on)} = 0.10\Omega$
$I_D = -14\text{A}$

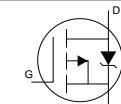


TO-220 FULLPAK

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	-55	—	—	V	$V_{GS} = 0V, I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.05	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = -1\text{mA}$ ⑥
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.10	Ω	$V_{GS} = -10V, I_D = -7.8\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
g_f	Forward Transconductance	4.2	—	—	S	$V_{DS} = 25V, I_D = -10\text{A}$ ⑥
I_{BS}	Drain-to-Source Leakage Current	—	—	-25	μA	$V_{DS} = -55V, V_{GS} = 0V$
		—	—	-250	μA	$V_{DS} = -44V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100	nA	$V_{GS} = -20V$
Q_g	Total Gate Charge	—	—	35	nC	$I_D = -10\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	7.9		$V_{DS} = -44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	16		$V_{GS} = -10V$, See Fig. 6 and 13 ④⑥
$t_{d(on)}$	Turn-On Delay Time	—	—	13	ns	$V_{DD} = -28V$
t_r	Rise Time	—	—	55		$I_D = -10\text{A}$
$t_{d(off)}$	Turn-Off Delay Time	—	—	30		$R_G = 13\Omega$
t_f	Fall Time	—	—	41		$R_D = 2.6\Omega$, See Fig. 10 ④⑥
L_D	Internal Drain Inductance	—	—	4.5	nH	Between lead, 6mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	—	7.5		
C_{iss}	Input Capacitance	—	—	620	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	—	280		$V_{DS} = -25V$
C_{rss}	Reverse Transfer Capacitance	—	—	140		$f = 1.0\text{MHz}$, See Fig. 5 ⑥

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-14	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①⑥	—	—	-68		
V_{SD}	Diode Forward Voltage	—	—	-1.3	V	$T_J = 25^\circ\text{C}, I_S = -7.8\text{A}, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	54	82	ns	$T_J = 25^\circ\text{C}, I_F = -10\text{A}$
Q_{rr}	Reverse Recovery Charge	—	110	160	nC	$dI/dt = -100\text{A}/\mu\text{s}$ ④⑥
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

② Starting $T_J = 25^\circ\text{C}$, $L = 3.6\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = -10\text{A}$. (See Figure 12)

⑤ $t=60\text{s}$, $f=60\text{Hz}$

③ $I_{SD} \leq -10\text{A}$, $di/dt \leq -290\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$,
 $T_J \leq 175^\circ\text{C}$

⑥ Uses IRF9Z34N data and test conditions

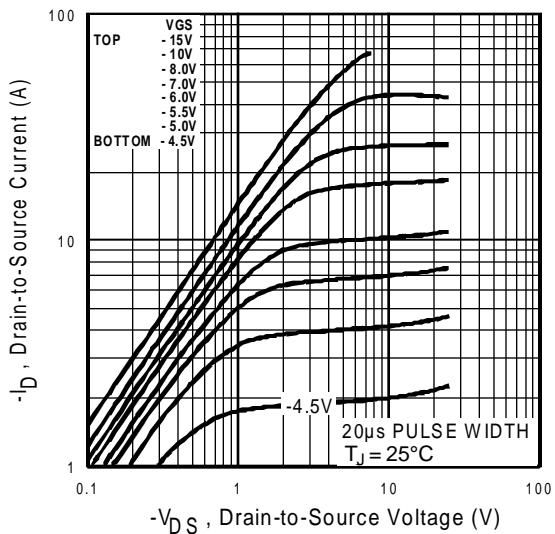


Fig 1. Typical Output Characteristics

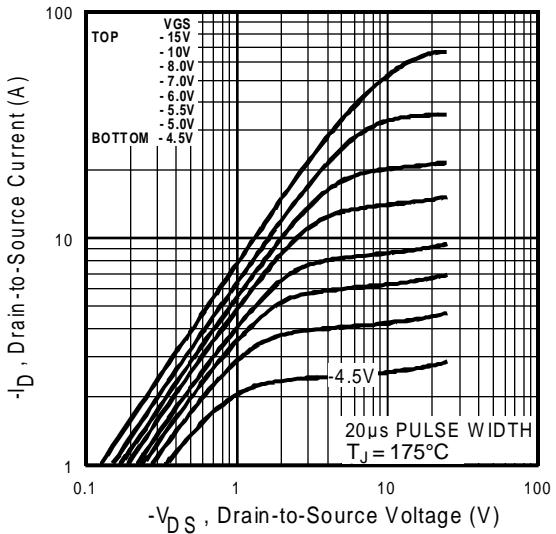


Fig 2. Typical Output Characteristics

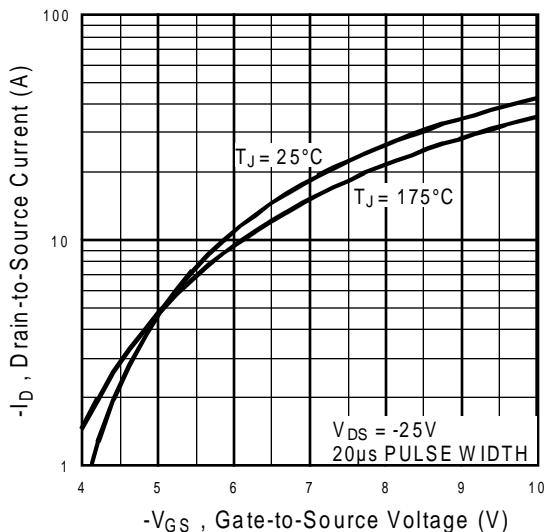


Fig 3. Typical Transfer Characteristics

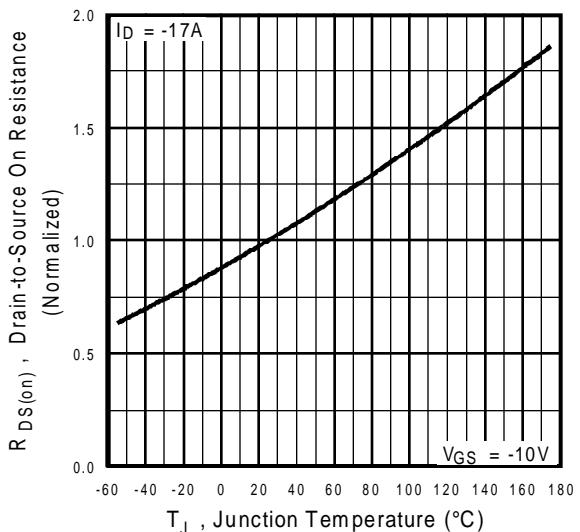


Fig 4. Normalized On-Resistance
Vs. Temperature

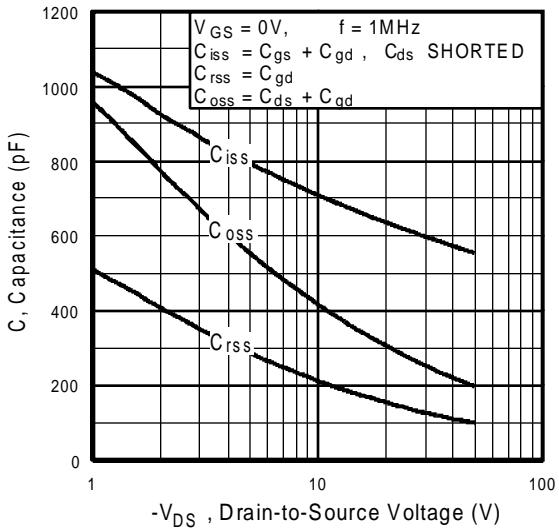


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

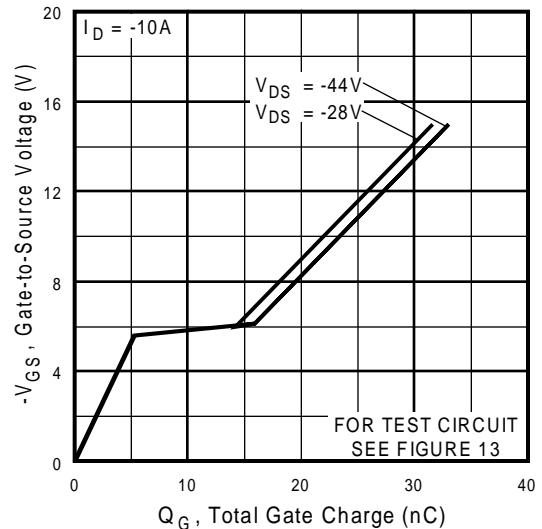


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

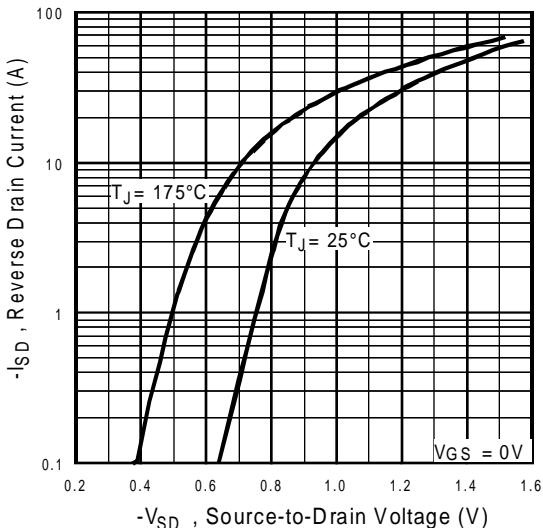


Fig 7. Typical Source-Drain Diode
Forward Voltage

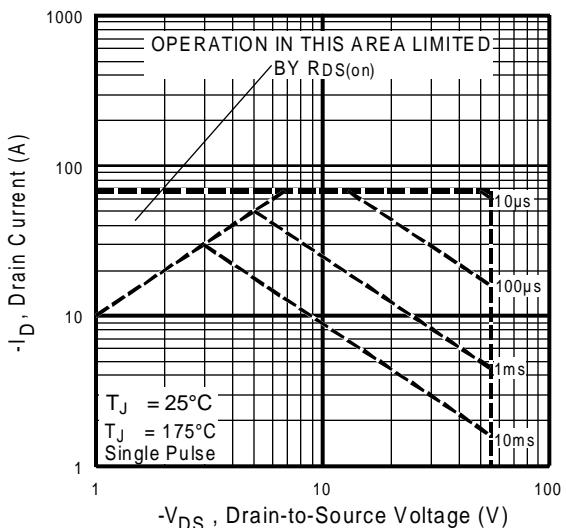


Fig 8. Maximum Safe Operating Area

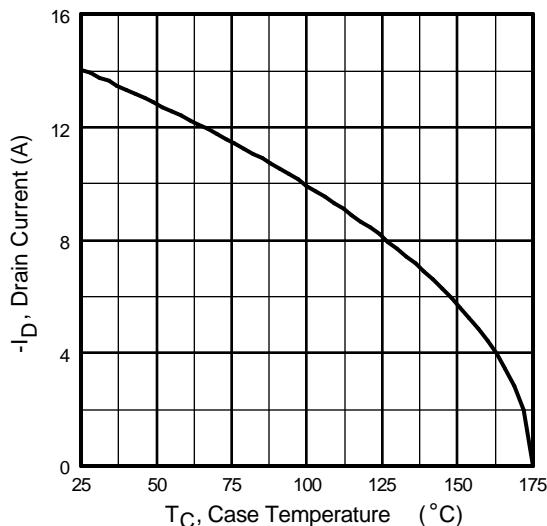


Fig 9. Maximum Drain Current Vs.
Case Temperature

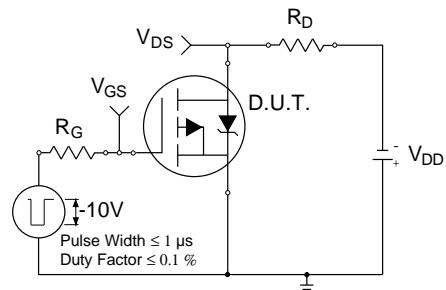


Fig 10a. Switching Time Test Circuit

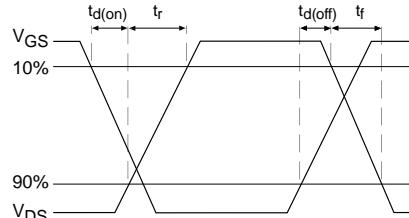


Fig 10b. Switching Time Waveforms

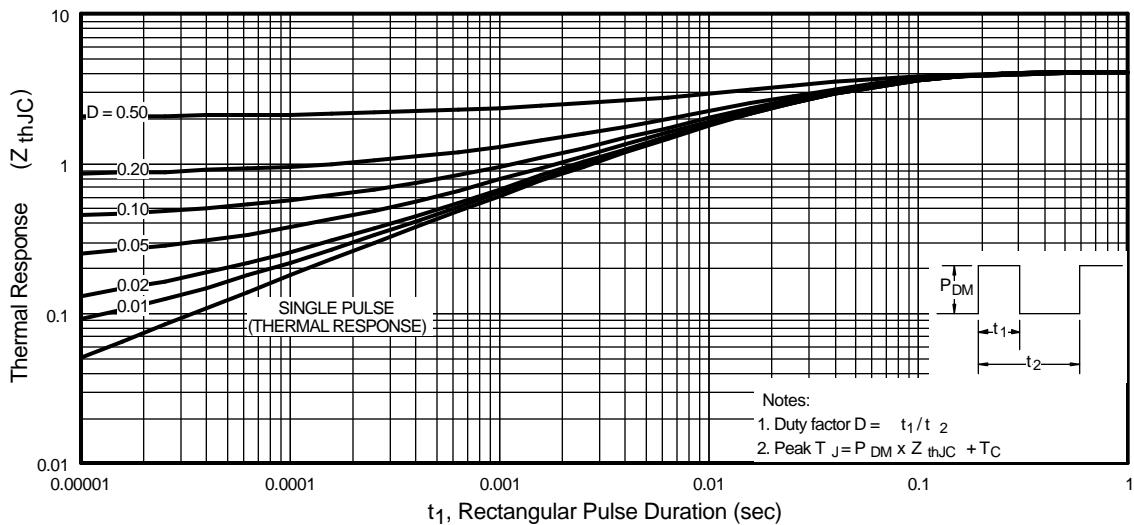


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

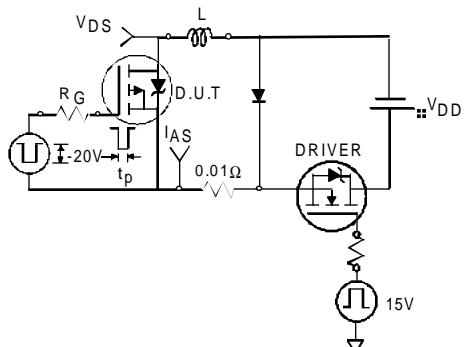


Fig 12a. Unclamped Inductive Test Circuit

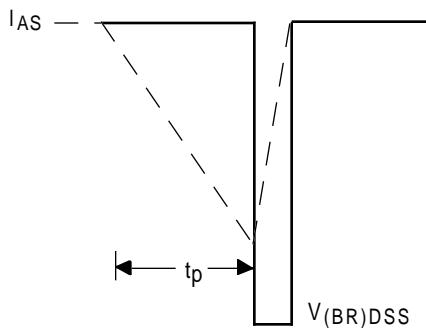


Fig 12b. Unclamped Inductive Waveforms

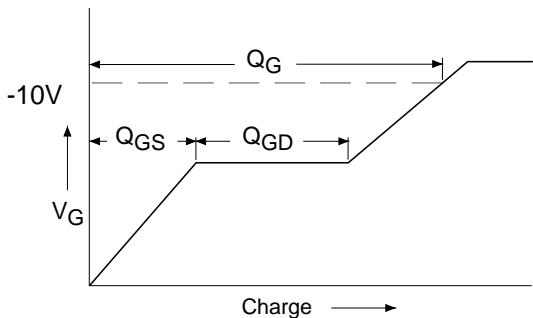


Fig 13a. Basic Gate Charge Waveform

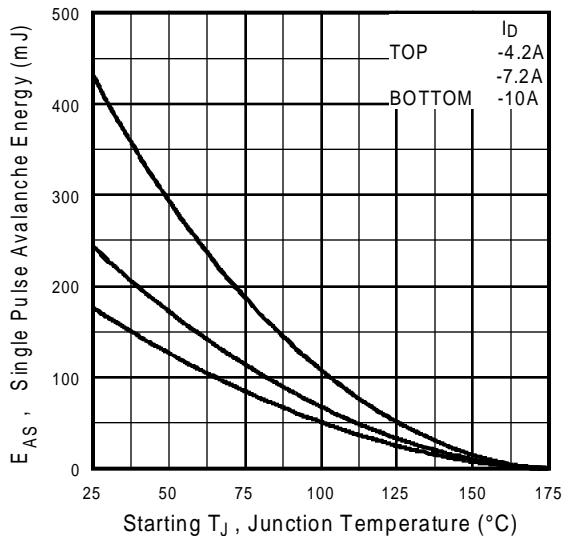


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

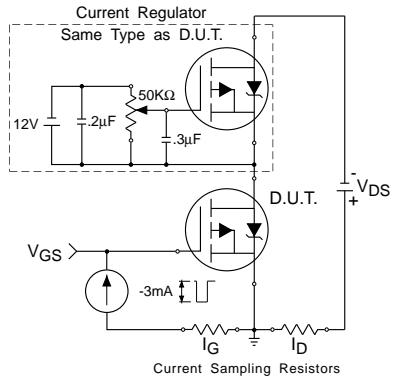
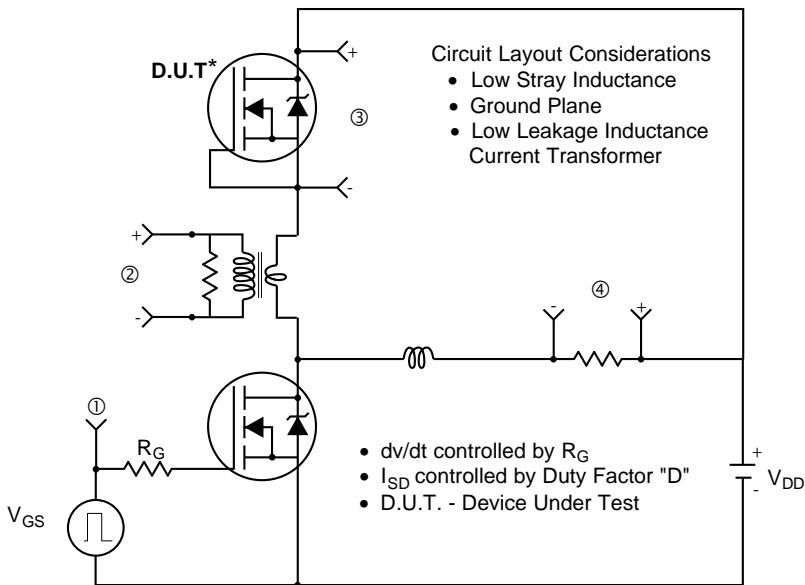
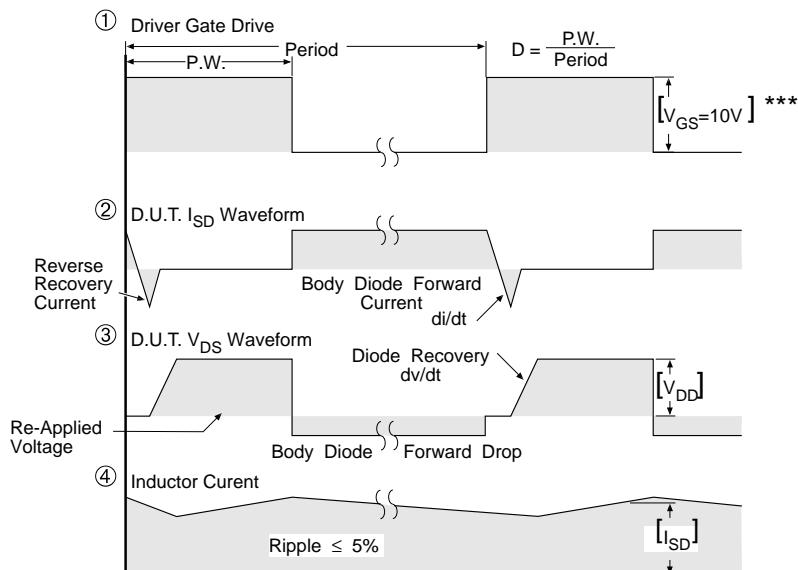


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* Reverse Polarity of D.U.T for P-Channel

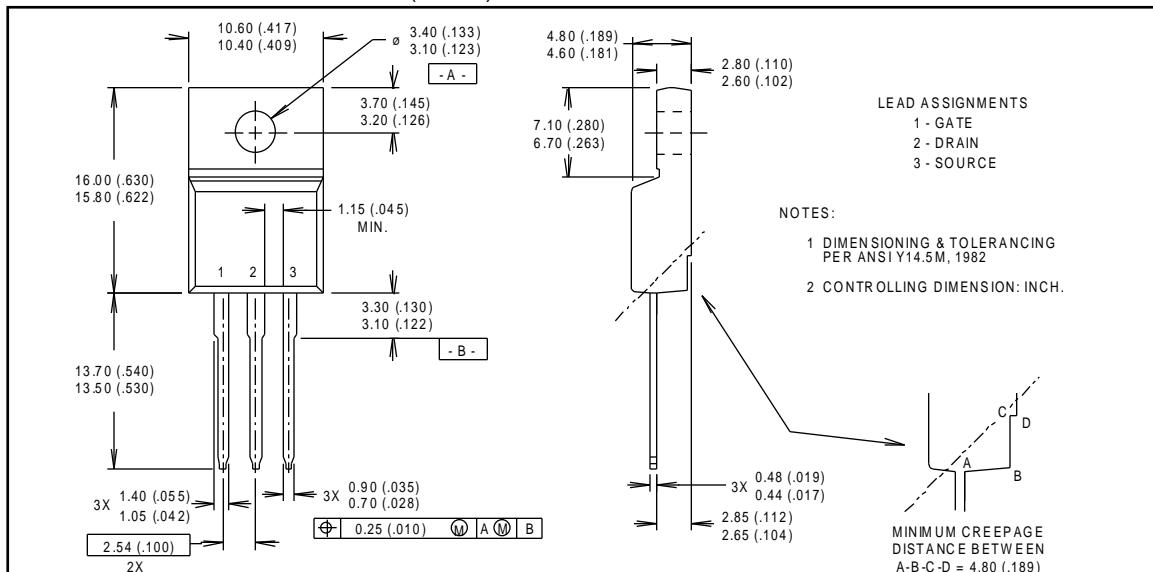


*** $V_{GS} = 5.0\text{V}$ for Logic Level and 3V Drive Devices

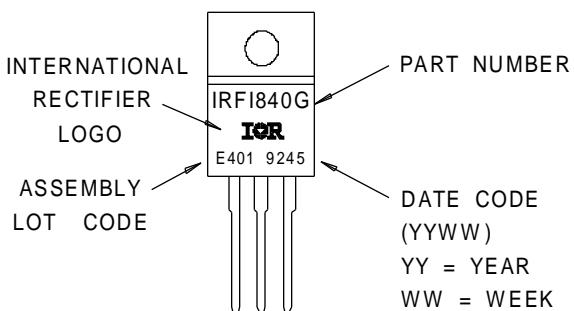
Fig 14. For P-Channel HEXFETS

Package Outline**TO-220 Fullpak Outline**

Dimensions are shown in millimeters (inches)

**Part Marking Information****TO-220 Fullpak**

EXAMPLE : THIS IS AN IRFI840G
WITH ASSEMBLY
LOT CODE E401



International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371